Abstract

The invention relates to a heat-activable pressure-sensitive adhesive. Provision is made for this heat-activable pressure-sensitive adhesive to comprise a polymer or copolymer formed from a monomer composition comprising at least 50% by weight of a compound of the formula $CH_2=CH(R_1)(COOR_2)$, wherein R_1 represents H or CH_3 and R_2 represents H or an alkyl chain having 1 to 30 carbon atoms, the polymer or copolymer having

a static glass transition temperature of -10°C to 120°C;

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a temperature activation range of 15°C or less; and

a molecular weight distribution M_w/M_n of 2.5 or less.